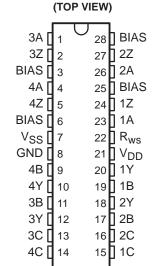
DW PACKAGE

SLLS187A - NOVEMBER 1994 - REVISED AUGUST 1995

- Four Independent Drivers and Receivers
- Driver Slew Rate Controlled by a Single Resistor
- Fast Driver Transition Times Down to 1.5 μs and Receiver Transition Times of 20 ns Typ
- Internal Thermal-Overload Protection
- RS-423-B Inputs and Outputs Designed to Withstand ±25 V
- ESD Protection Exceeds 2000 V Per MIL-STD-833C Method 3015
- LinBICMOS™ Process Technology

description

The SN75LBC784 performs as four independent RS-423-B driver/receiver pairs designed to interface data terminal equipment (DTE) with data circuit-terminating equipment (DCE) at rates up to 120 kbps and distances to 1.2 km. The SN75LBC784 provides an upgrade to the RS-232 serial interface and can be backward compatible with existing serial ports while offering the higher performance required by new faster peripherals, such as v.34 (v.fast) modems. The RS-232 standard, and subsequent revisions, only support data rates up to 20 kbps over about 15 meters of cable. For RS-423-B the data rate is increased to 120 kbps and transmission distance to 1.2 km by reducing the maximum output signal swing, increasing the driver output current, and reducing the receiver input voltage thresholds.



FUNCTION TABLE

	INPUTS	3	OUT	PUTS
Α	В	С	Z	Υ
L	L	Н	Н	Н
Н	L	Н	Н	L
L	Н	L	L	Н
Н	Н	L	L	L
L	L	L	?	Н
Н	L	L	?	L
L	Н	Н	?	Н
Н	Н	Н	?	L

H = high level, L = low level,

X = irrelevant, Z = high impedance (off)

? = indeterminate

The receivers consist of differential comparators with hysteresis and resistive attenuation on the inputs. The resistive attenuation improves the input common mode range and also provides additional protection from ESD and over-voltage stress. The differential and common mode input impedances are sufficiently high to meet RS-423-B. When a differential voltage input of 500 mV is applied across the entire common mode range (see Figure 5), the receiver characteristics and bias voltage allow the receiver to remain in its intended binary state.

The drivers meet all RS-423-B specifications with built-in current limits and thermal-overload protection. Slew-rate controlling circuitry is included in the design, which is adjusted to suit the application by means of an external resistor (R_{WS}). The slew rate controlling circuitry also has a default mode – if the R_{WS} pin is shorted to 5 V externally, the transistion time defaults to approximately 1.5 ms. The BIAS input, when shorted to 5 V externally, provides the internal node voltages. The receiver is compatible to RS-232 with the use of external input resistors to meet the RS-232 input resistance specification of 3 k Ω to 7 k Ω .

The SN75LBC784 is characterized for operation over the temperature range of 0°C to 70°C.



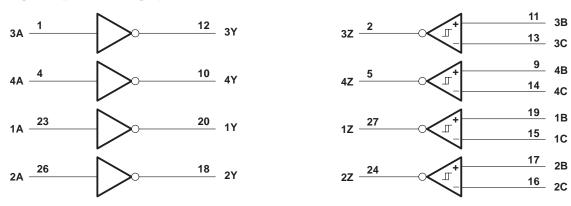
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Positive supply voltage, V _{DD} (see Note 1)	
Negative supply voltage, V _{SS}	14 V
Bias voltage, V _{bias}	5.75 V
Receiver input voltage range	30 V to 30 V
Driver input voltage range	0.5 V to 5.75 V
Driver output voltage range (supplies at 0 V)	30 V to 30 V
Driver output voltage range (supplies at ±12 V)	25 V to 25 V
Continuous power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	—65°C to 150°C
Case temperature for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR [†] ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
DW	1348 mW	10.8 mW/°C	862 mW		

[†]Derating factors are the inverse of the junction-to-ambient thermal resistance when board-mounted with no air flow.

recommended operating conditions

					MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}					10.8	12	13.2	V
Supply voltage, VSS					-10.8	-12	-13.2	V
Bias voltage, V _{bias}					2	5	5.5	V
High-level input voltage, VIH	Driver				2			V
Low-level input voltage, V _{IL}	Driver						0.8	V
High-level output current, IOH	Receive	r					-4	mA
Low-level output current, IOL	Receive	r					4	mA
Rws slew rate control resistor					20	82	820	kΩ
Operating free-air temperature, T _A				0		70	°C	



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature, V_{DD} = 10.8 V to 13.2 V, V_{SS} = -10.8 V to -13.2 V, T_A = 0°C to 70°C (unless otherwise noted)

PARAMETER		TEST CO	TEST CONDITIONS			MAX	UNIT
Vон	High-level output voltage	Open circuit or R _L = 4	1 50 Ω	4	5.5	6	V
VOL	Low-level output voltage	Open circuit or R _L = 4	1 50 Ω	-6	-5.5	-4	V
lіН	High-level input current	$V_{ } = 2.4 \text{ V to } 5.5 \text{ V}$				100	μΑ
I _{IL}	Low-level input current	V _I = 0 V to 0.8 V		-100			μΑ
IO	Output leakage current	$V_{DD} = V_{SS} = 0$,	V _O = ±6 V	-100		100	μΑ
IOS(H)	High-level short circuit output current	V _I = 5 V,	V _O = 0	15		45	mA
IOS(L)	Low-level short circuit output current	V _I = 0,	V _O = 0	-45		-15	mA
la-a	Cumply ourrant	No load		10	12	mA	
IDD	Supply current	$R_L = 450 \Omega$	$R_L = 450 \Omega$			70	IIIA
ISS Supply current		No load		-10	-12	mA	
		$R_L = 450 \Omega$		-60	-70	IIIA	
I _{bias}	Bias current		•			400	μΑ

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, V_{DD} = 10.8 V to 13.2 V, V_{SS} = -10.8 V to -13.2 V, T_A = 0°C to 70°C (unless otherwise noted)

PARAMETER		TEST CONDIT	MIN	TYP	MAX	UNIT		
			$R_{WS} = 0 k\Omega$		1.5			
			$R_{WS} = 20 \text{ k}\Omega$	1.5	2.1	2.7		
tTLH	Transition time, low-to-high level (see Figure 1)		$R_{WS} = 82 \text{ k}\Omega$	5	8	11	μs	
			$R_{WS} = 820 \text{ k}\Omega$		80			
		$R_L = 450 \Omega$, $C_L = 50 pF$,	$R_{WS} = 0 k\Omega$		1.5			
		$V_{WS} = 5 V$	$R_{WS} = 20 \text{ k}\Omega$	1.5	2.1	2.7		
tTHL	Transition time, high-to-low level (see Figure 1)		$R_{WS} = 82 \text{ k}\Omega$	5	8	11	μs	
			$R_{WS} = 820 \text{ k}\Omega$		80			
SR	Output slew rate		Rws = $20 \text{ k}\Omega$			15	V/μs	
t _{sk}	Output skew (see Figure 4) tpHL - tpLH		$R_{WS} = 82 \text{ k}\Omega$			1	μs	

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature, V_{DD} = 10.8 V to 13.2 V, V_{SS} = -10.8 V to -13.2 V, T_A = 0°C to 70°C (unless otherwise noted)

PARAMETER		TEST CO	TEST CONDITIONS			MAX	UNIT
V 5 %						200	mV
V _{IT+}	Positive input threshold voltage	With 500 Ω series resis	tor			400	IIIV
\/	No motive input threehold veltore					-200	mV
VIT-	Negative input threshold voltage	With 500 Ω series resis	tor			-400	IIIV
ı.	Input ourront	V _I = 10 V	Other input to CND		1.3	3.25	mA
II Input current	input current	V _I = -10 V	Other input to GND	-3.25	-1.3		IIIA
V _{hys}	Hysteresis (V _{IT+} – V _{IT} _)		-	20	40	150	mV
V	Lligh level output voltage (see Note 2)	I _O = -20 μA	3.5		5	V	
VOH	High-level output voltage (see Note 2)	$I_O = -4 \text{ mA}$	2.4		5	V	
VOL	Low-level output voltage	I _O = 20 μA to 4 mA	I _O = 20 μA to 4 mA			0.4	V
I _{RX}	RX short circuit current					50	mA
V_{ID}	Differential input voltage	Receiver inputs open circuit		1.6	2.1	2.6	V
Vofs	Fail safe output voltage	See Note 3	See Note 3				V

NOTES: 2. Device has an internal RX supply regulator. Maximum RX logic output voltage under no load is thus defined by an internal voltage value. This is nominally set to 4.5 V with a tolerance of ±5%.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

test conditions: V_{DD} = 10.8 V to 13.2 V, V_{SS} = -10.8 V to -13.2 V, T_A = 0°C to 70°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	NOM	MAX	UNIT
^t PLH	Propagation Delay time low-to-high (see Figure 2)			0.15	1	
tPHL	Propagation delay time high-to-low (see Figure 2)	C _I = 50 pF		0.15	'	μs
tTHL	Transition time high-to-low (see Figure 3)	CL = 50 pr		20	200	
tTLH	Transition time low-to-high (see Figure 3)		20	200	ns	



^{3.} One input at ground, other input open circuit, $I_{O} = -20 \,\mu\text{A}$, or both open circuit.

PARAMETER MEASUREMENT INFORMATION

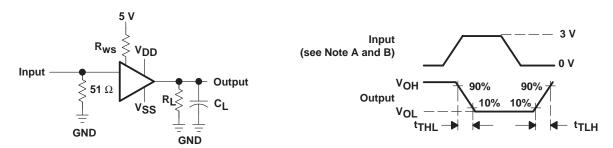


Figure 1. Driver Transition Times

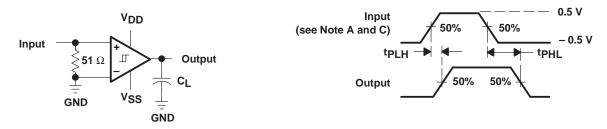


Figure 2. Receiver Propagation Delay Times

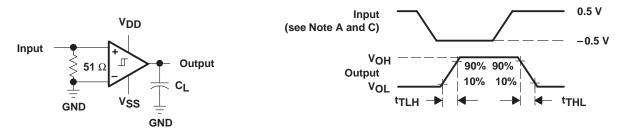


Figure 3. Receiver Transition Times

NOTES: A. C_L includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: $t_{\Gamma} \le 10$ nS, $t_{f} < 10$ nS, $t_{Q} = 50$ Ω , PRR ≥ 5 kHz, duty cycle 50%, $V_{max} = 3$ V, $V_{min} = 0$ V.
- C. The input pulse is supplied by a generator having the following characteristics: $t_f \le 10$ nS, $t_f < 10$

PARAMETER MEASUREMENT INFORMATION

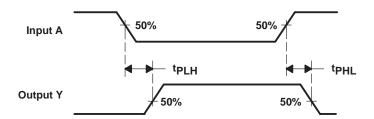


Figure 4. Skew Definition Times

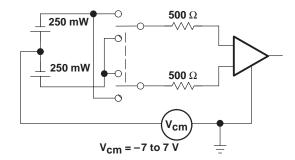


Figure 5. Receiver Input Balance Test





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75LBC784DW	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC784DWG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC784DWR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC784DWRG4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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